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IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF:

:

Eric PILAT

: EXAMINER: EDMONDSON, L. R.

SERIAL NO: 09/926,402

:

FILED: OCTOBER 26, 2001

: GROUP ART UNIT: 1725

~~FOR: METHOD FOR THE MAKING OF SOLDER CONNECTION PADS ON A~~
SUBSTRATE AND GUIDE FOR THE IMPLEMENTATION OF THE METHOD

AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

In response to the Office Action dated November 20, 2002, please amend the above-identified application as follows:

IN THE CLAIMS

A clean copy of the claims incorporating any amendment is shown below.

Please amend Claims 1 and 13 as follows:

1. (Amended) A method for making balls or solder connection pads directly on an electrically conductive connection-receiving zone of an electric component, the method comprising an operation for the injection of conductive liquid alloy into a guide open at one end placed so as to face the connection-receiving zone of the component, wherein the guide is formed by two separable parts, a mold and an injection matrix, the mold and the injection

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